

# Case Studies



## GaN FET Simulation

\*P. K. Saxena *at. el.*, Atomistic Level Process to Device Simulation of GaNFET Using TNL TCAD Tools, [Book Chapter](#), © [Springer Nature](#) (2020) 176, Lecture Notes in Electrical Engineering ISBN 978-981-15-5261-8 ISBN 978-981-15-5262-5 (eBook)



# GaNFET Epitaxial Growth

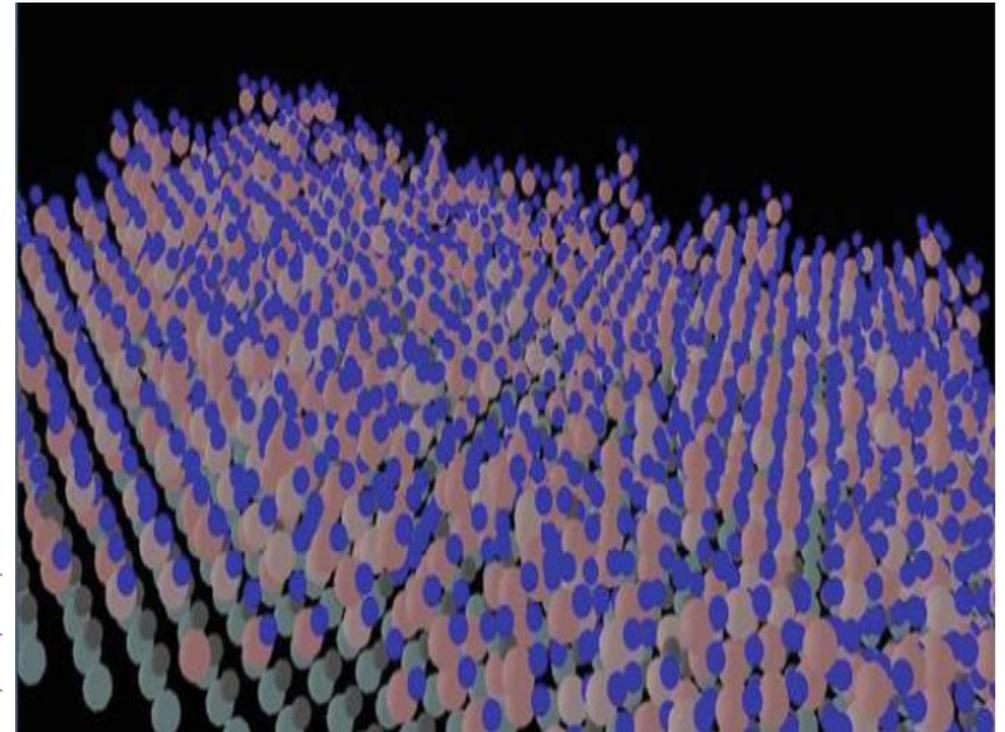


Epi-growth has been done with the following process parameters:

Parameters	Values	Unit
Time	30	s
Temperature	800	°C
Surface energy	2	eV
Desorption barrier energy	4	eV
Schwoebel barrier	0.002	eV
Incorporation barrier	0.05	eV
Nearest neighbor attraction	0.05	eV

Precursors and gas ambience used during simulation

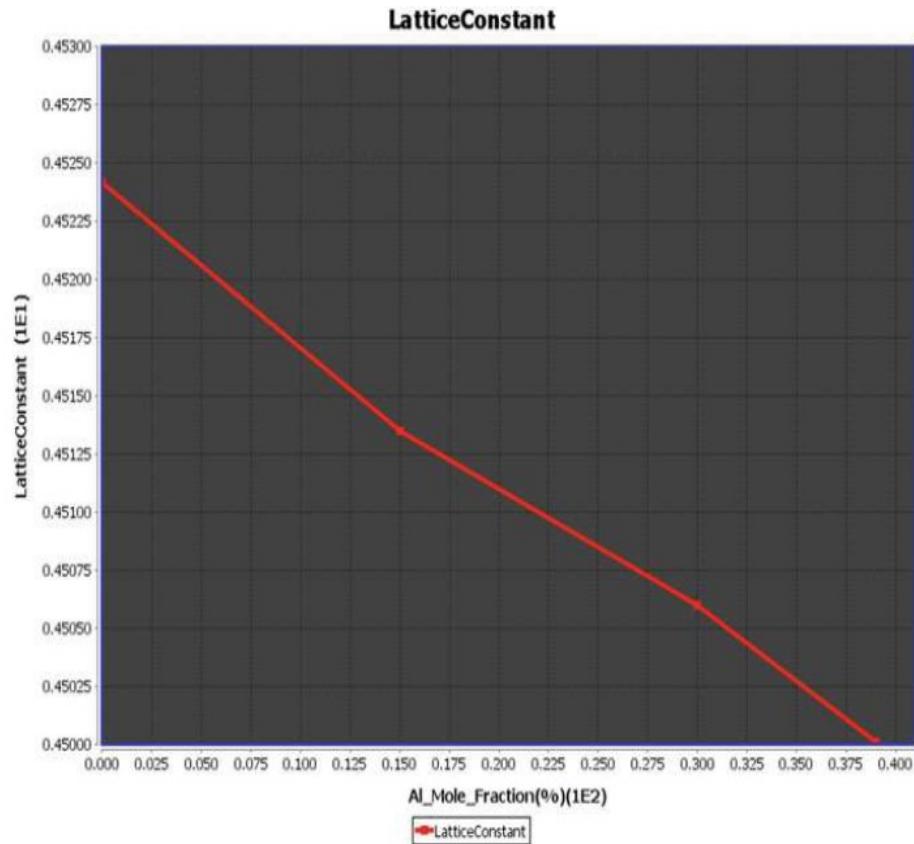
Materials	Partial pressure		
	Ga (mbar)	Al (mbar)	N2 (mbar)
GaN	0.3	0.0	3.0
Ga <sub>0.85</sub> Al <sub>0.15</sub> N	0.3	0.03	3.0
Ga <sub>0.7</sub> Al <sub>0.3</sub> N	0.28	0.05	3.0
Ga <sub>0.61</sub> Al <sub>0.39</sub> N	0.25	0.10	3.0



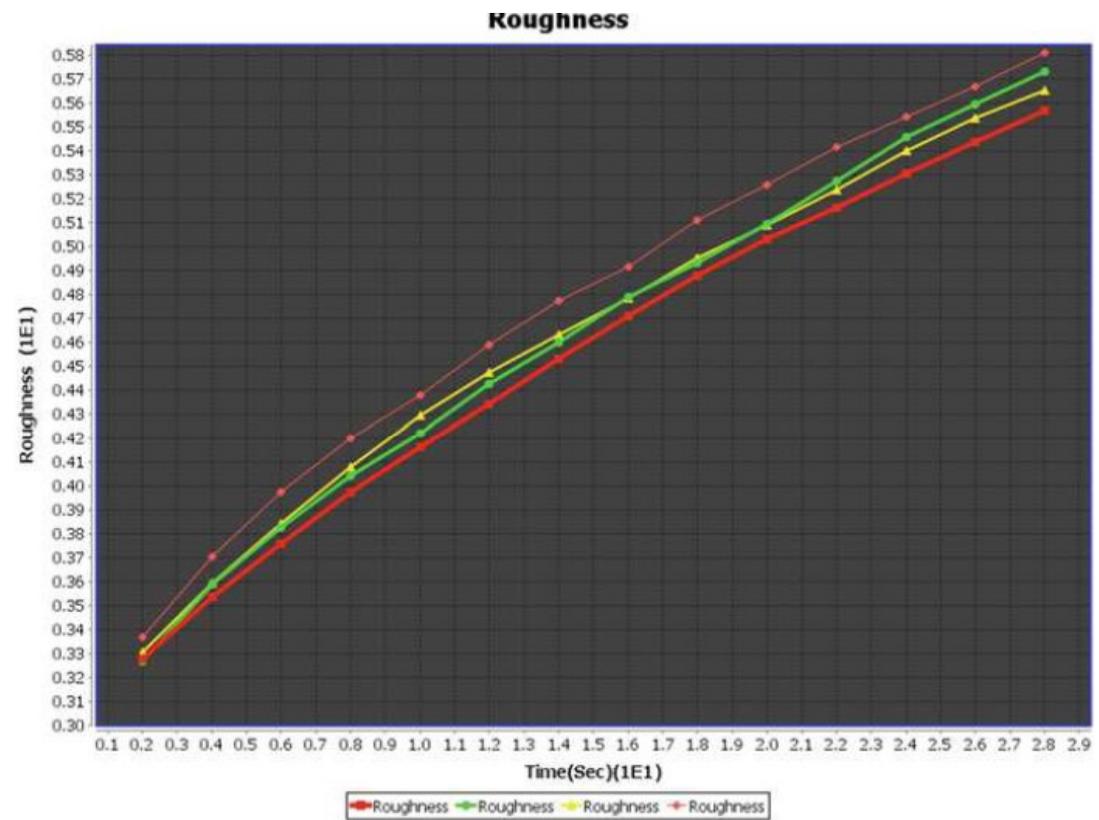
# GaNFET Case Studies



Variation of lattice constant with Al mole fraction



Surface roughness at the interface of AlGaN/GaN



# GaNFET Case Studies

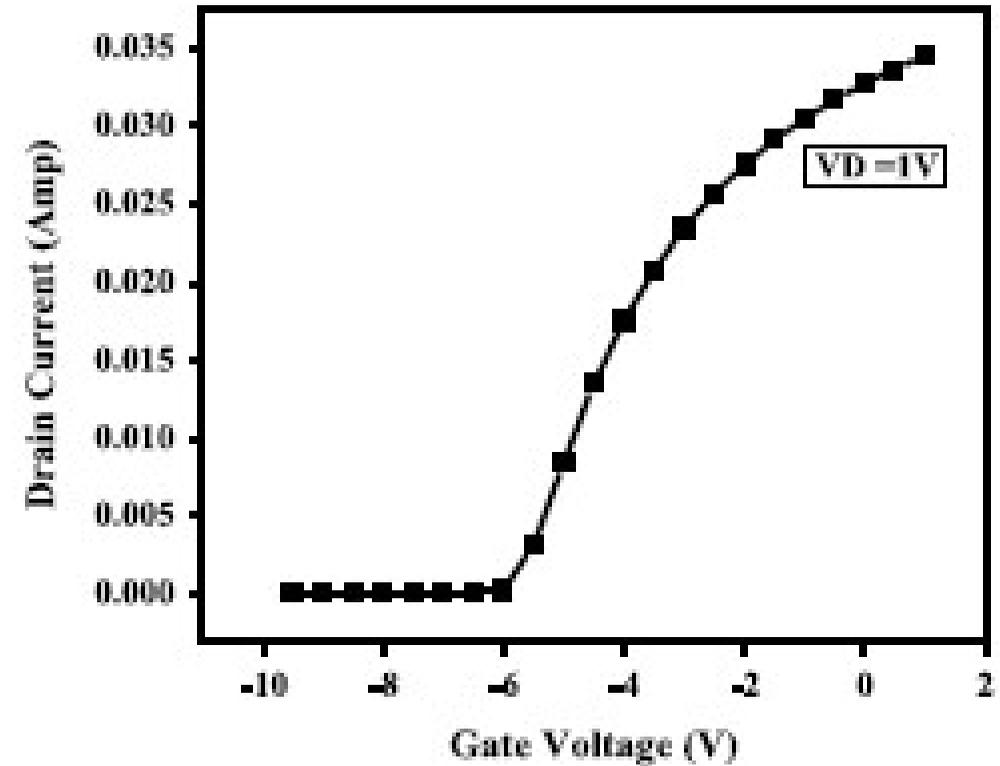
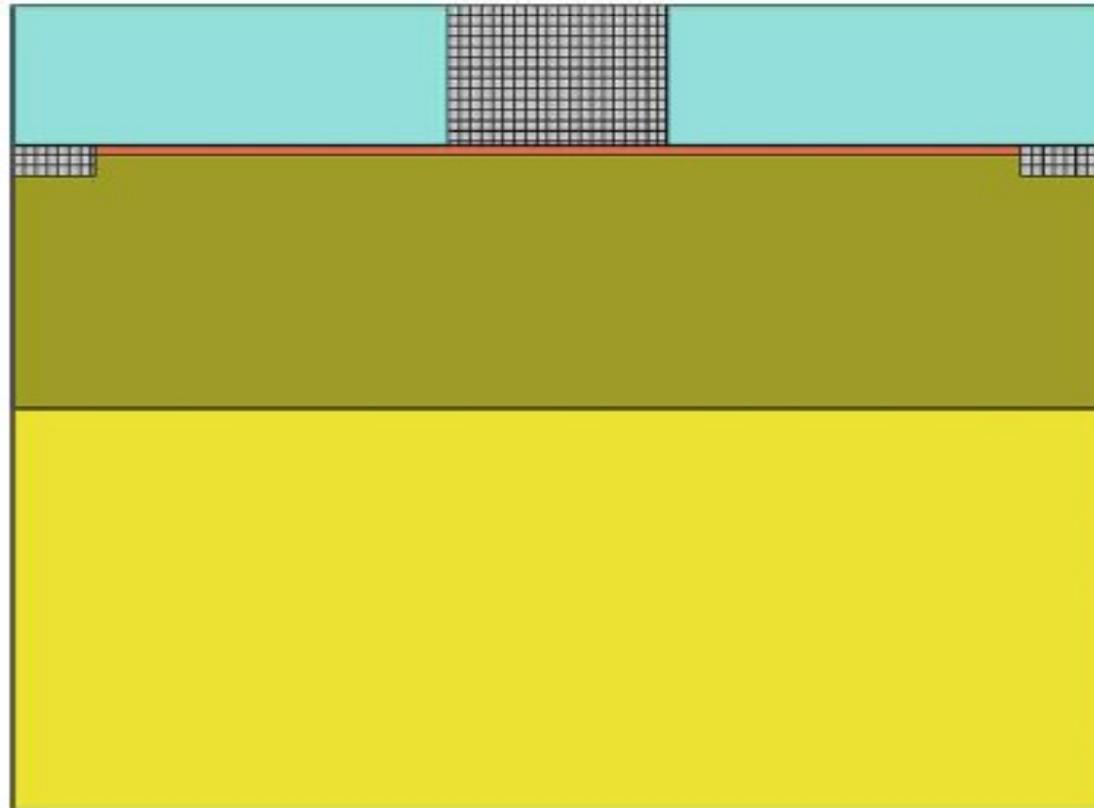
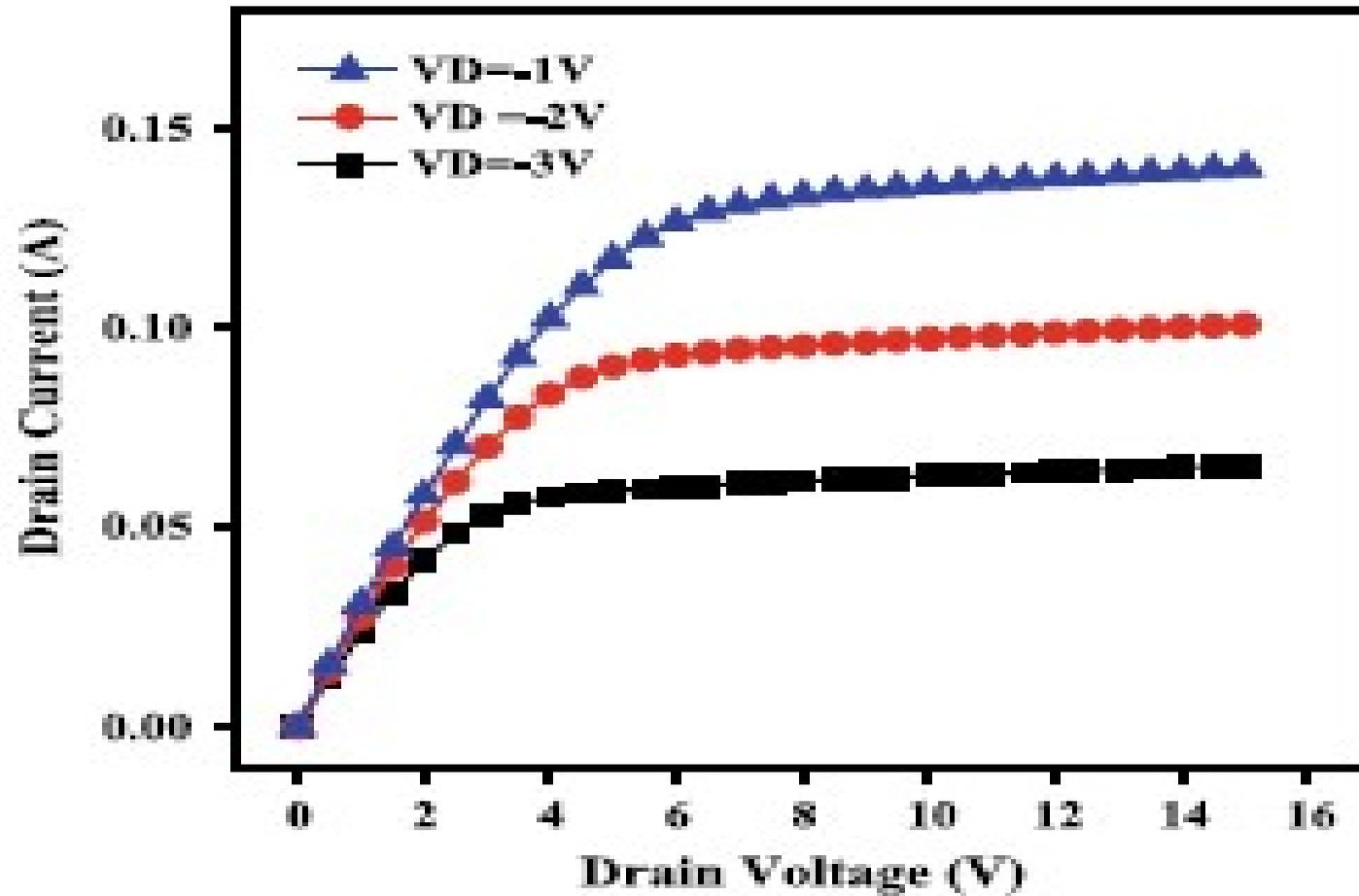


Fig. 9 Device structure with 25 nm thick AlGaIn/GaN layer grown on SiC (100) substrate

# GaNFET Case Studies



# Optical Device



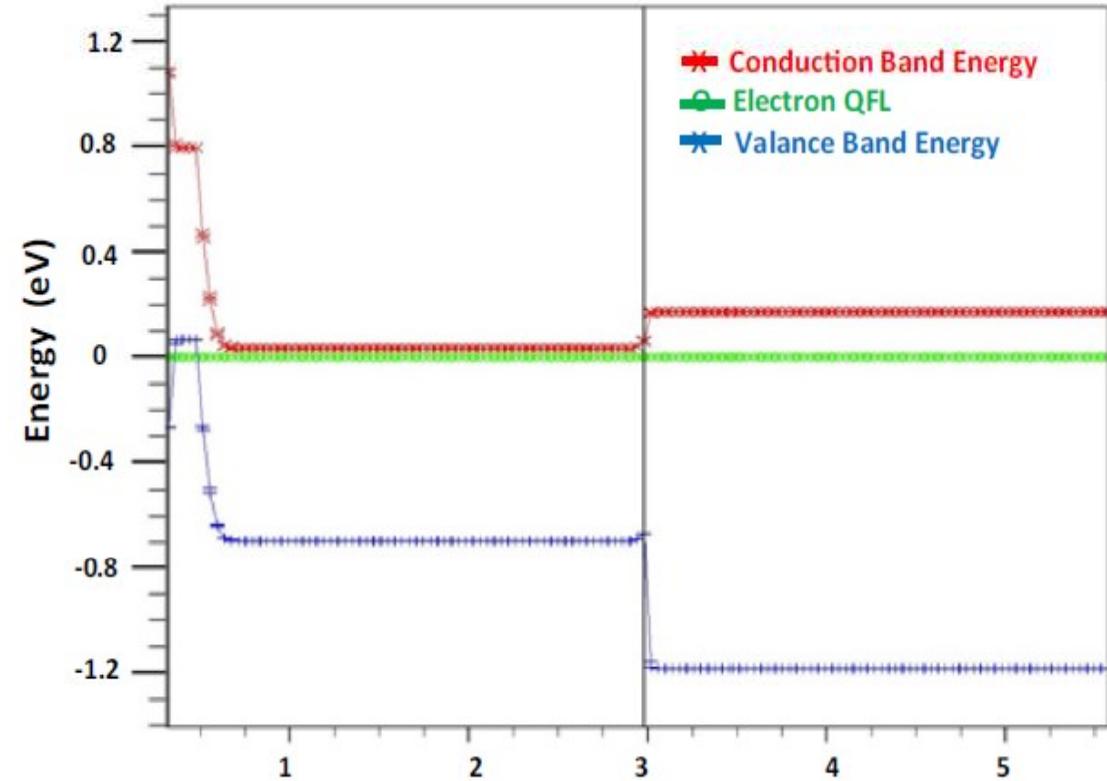
## InGaAs/InP Infrared Photodetector

\*P. K. Saxena *at. el.*, Numerical simulation of  $\text{In}_x\text{Ga}_{1-x}\text{As}/\text{InP}$  PIN photodetector for optimum performance at 298 K, [\*Optical and Quantum Electronics\*](#) (2020) 52:374

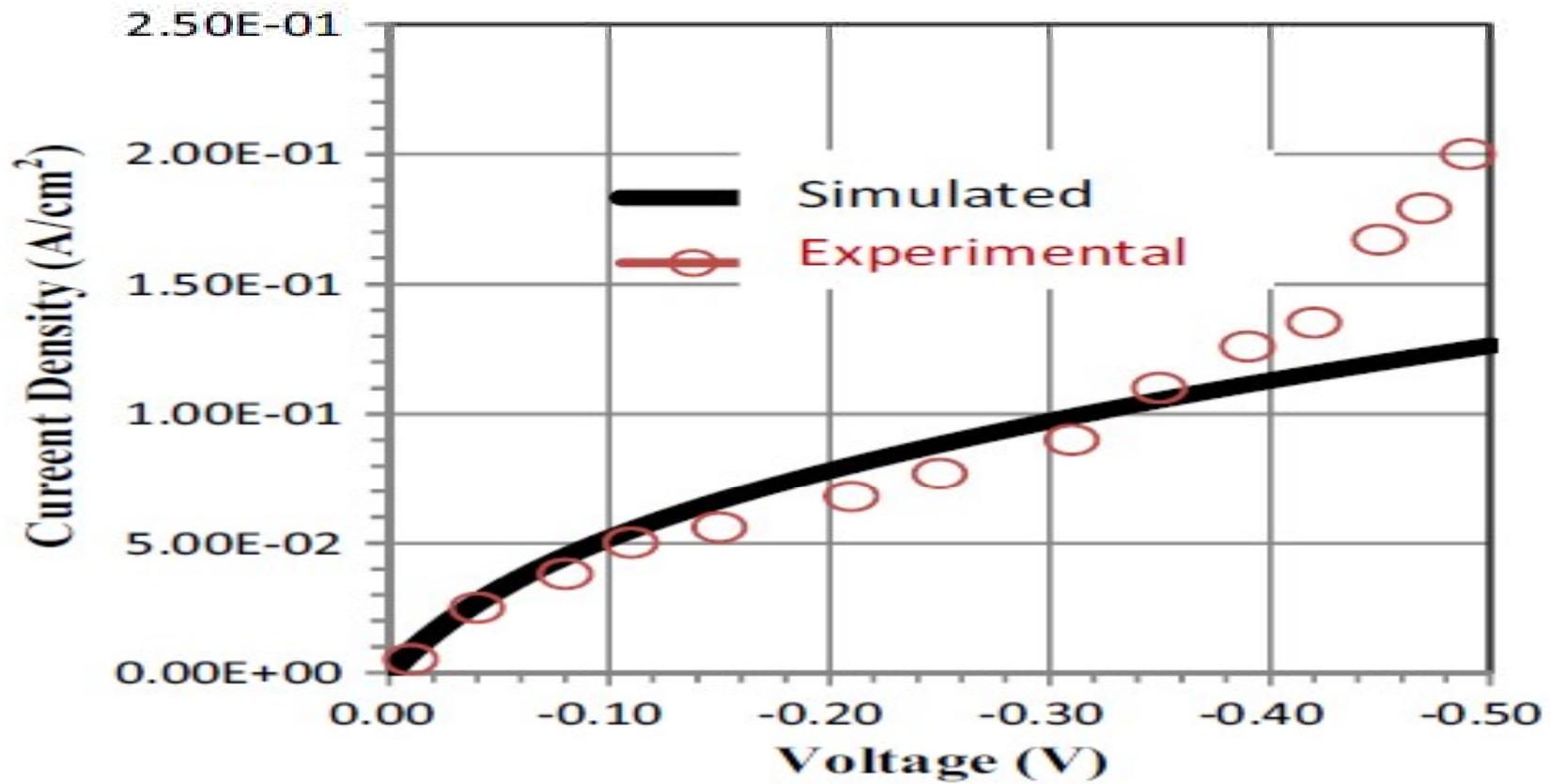
# Infrared Detector



$p^+$ $\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$ (150 nm)	$p$ - InP	$i$ - $\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$ (2.5 $\mu\text{m}$ )	$n$ -InP (2.6 $\mu\text{m}$ )
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# I – V Characteristics

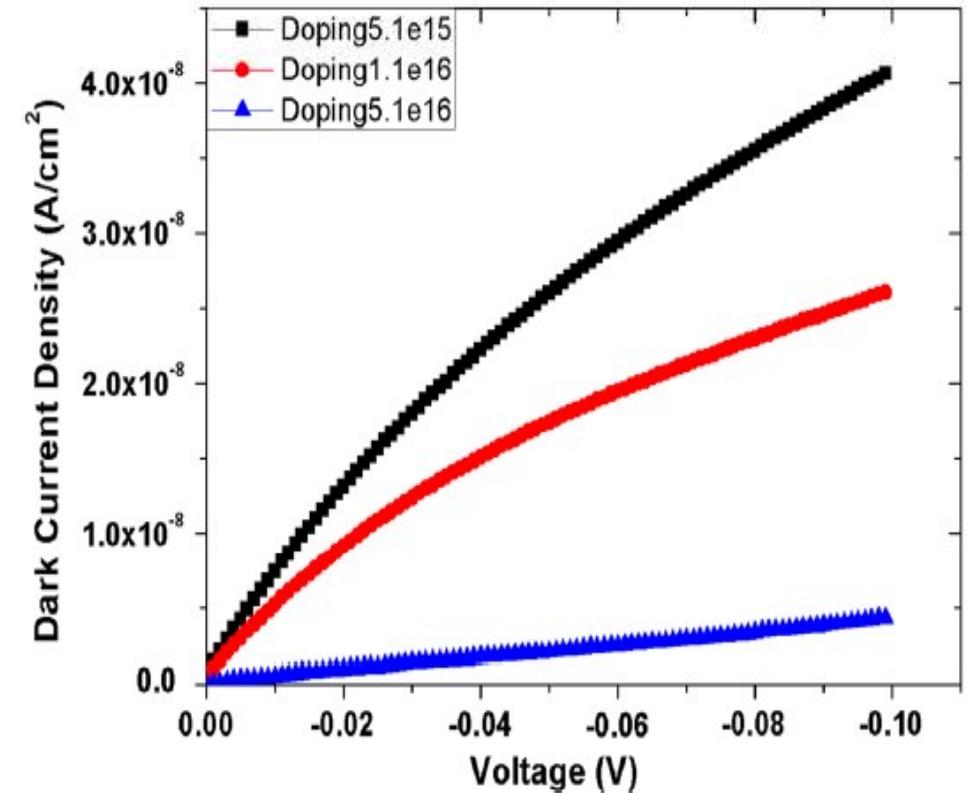


# Infrared Detector

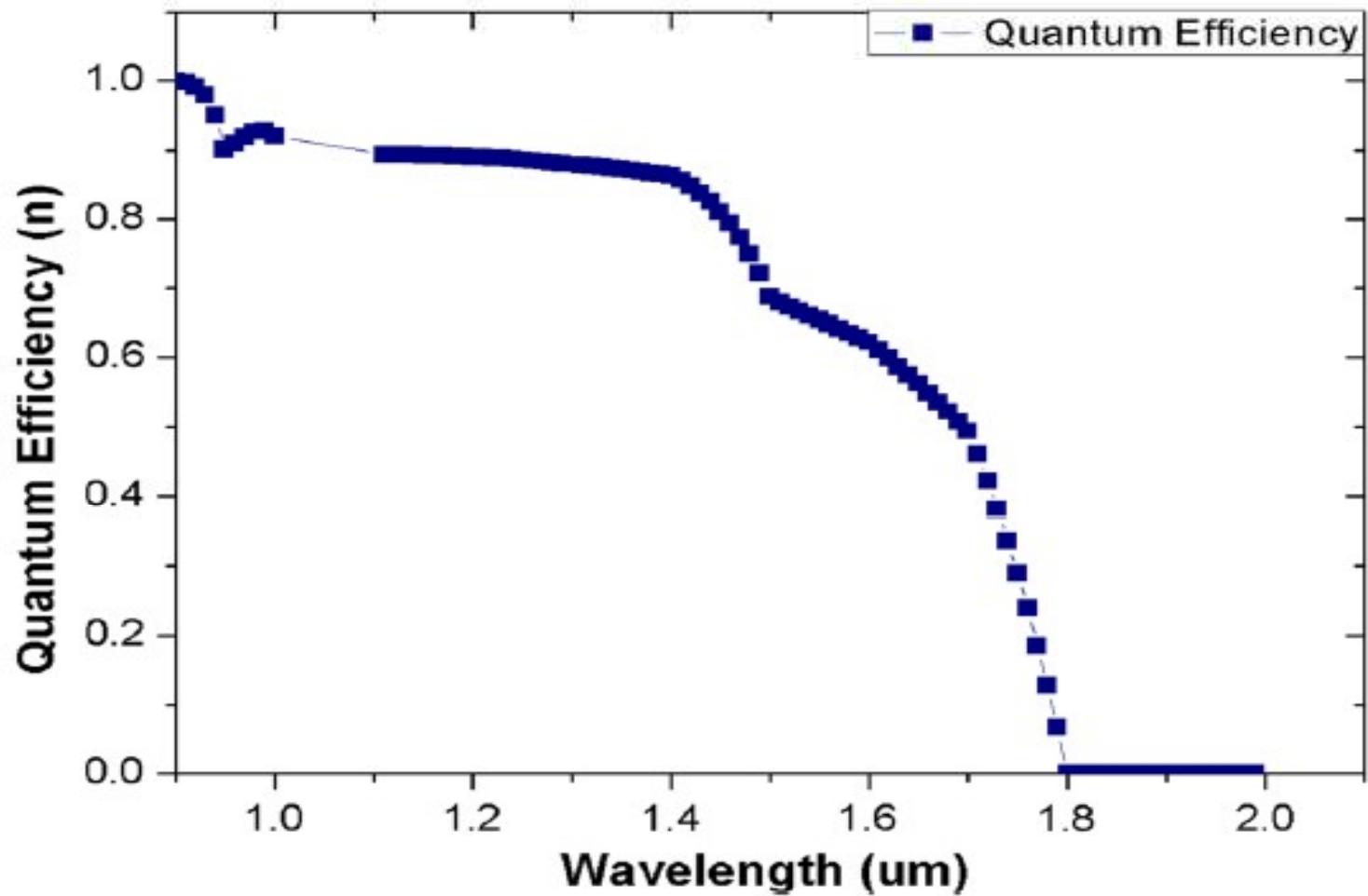


Table 1 The current density values for different doping dose at specified absorbing layer thickness

Doping dose ( $\text{cm}^{-3}$ )	Current density at specified absorbing layer thickness ( $\text{A}/\text{cm}^2$ )		
	2 $\mu\text{m}$	2.5 $\mu\text{m}$	3 $\mu\text{m}$
$5.1 \times 10^{15}$	$2.53 \times 10^{-07}$	$2.53926 \times 10^{-07}$	$2.54 \times 10^{-07}$
$1.1 \times 10^{16}$	$1.62 \times 10^{-07}$	$1.63 \times 10^{-07}$	$1.63 \times 10^{-07}$
$5.1 \times 10^{16}$	$2.6456 \times 10^{-08}$	$2.6898 \times 10^{-08}$	$2.7595 \times 10^{-08}$



# Quantum Efficiency



# FDSOI MOSFET

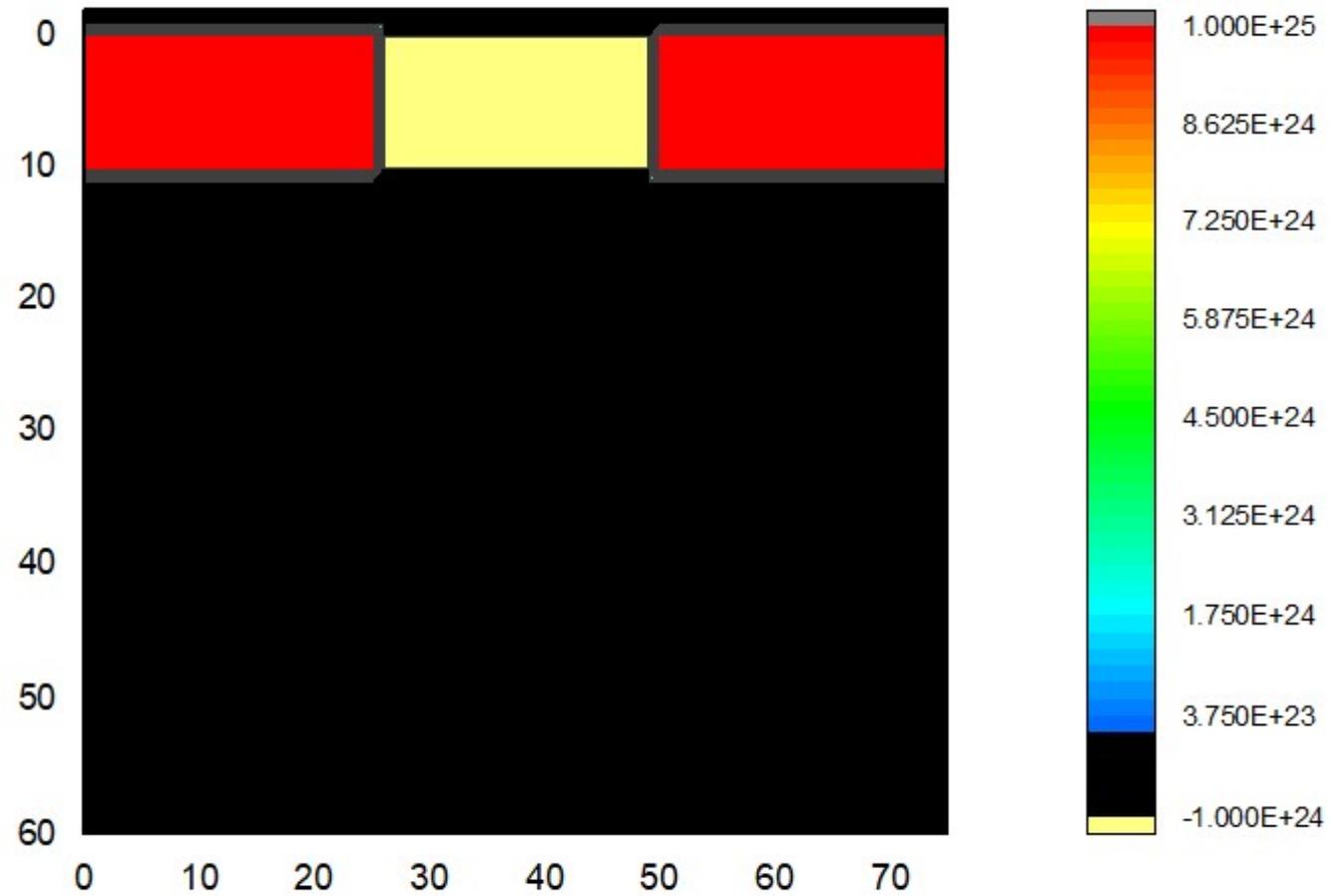


## FDSOI MOSFET

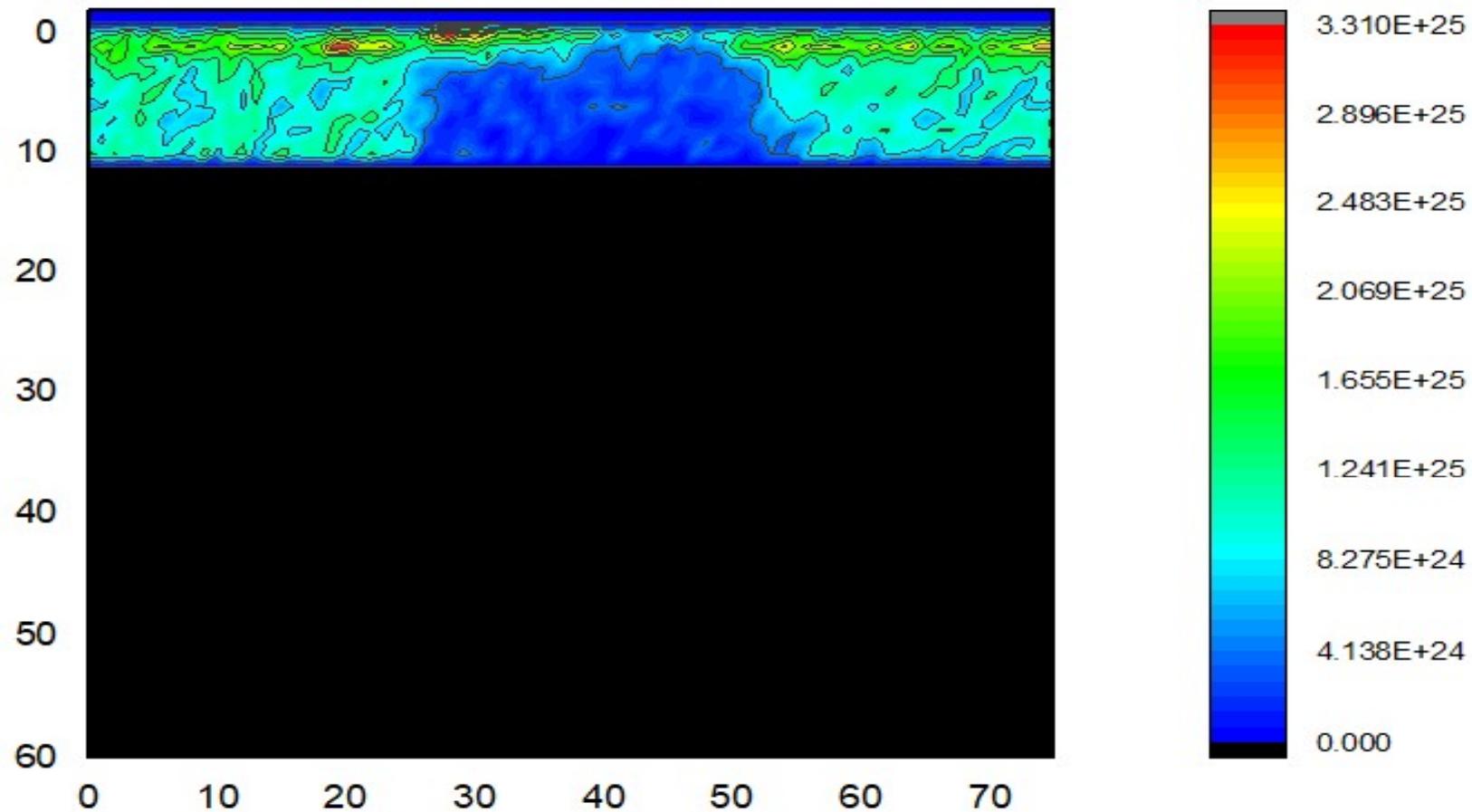
\*P. K. Saxena *at. el.*, A Comparative Study for Scaling FDSOI Technology up to 7nm –Based on Particle device Simulation, *Jaournal of Nano & Optoelectronics*(2020), under Review.



# FDSOI MOSFET



# FDSOI : CARRIERS DENSITY



# FDSOI MOSFET RESULTS



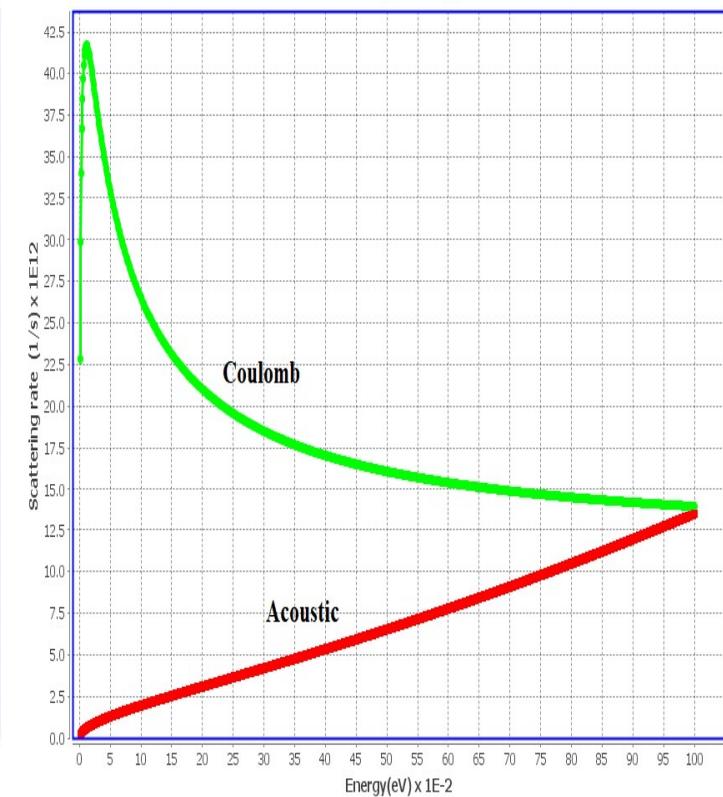
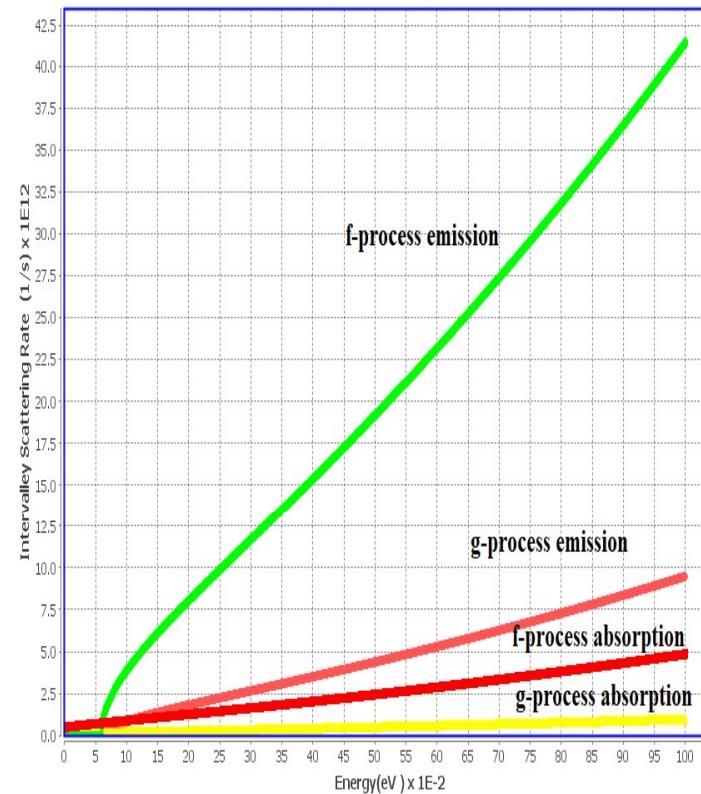
Structure Parameters	Nodes (nm)	14nm	10nm	7nm	14nm	10nm	7nm
		Single Gate			Double Gate		
	L <sub>eff</sub> (nm)	22	14	10	22	14	10
	W <sub>eff</sub> (nm)	10		8	10		8
	T <sub>ox</sub> (nm)	1	0.85	0.75	0.75	0.85	0.75
	Doping (/cm <sup>3</sup> )	1×10 <sup>24</sup>	5×10 <sup>24</sup>	2×10 <sup>25</sup>	2×10 <sup>25</sup>	5×10 <sup>24</sup>	2×10 <sup>25</sup>
	T <sub>soi</sub> (nm)	40	30	20	20	30	20
Device Parameters	V <sub>th</sub> (mV)	0.3	0.22	0.2	0.2	0.4	0.5
	SS (/mV/dec)	63.3	67.9	82.9	82.9	87.4	72.2
	gm (mS/μm)	0.252	0.437	0.499	0.499	0.494	0.449

# FDSOI TECHNOLOGY UP TO 7NM



## Scattering Rates

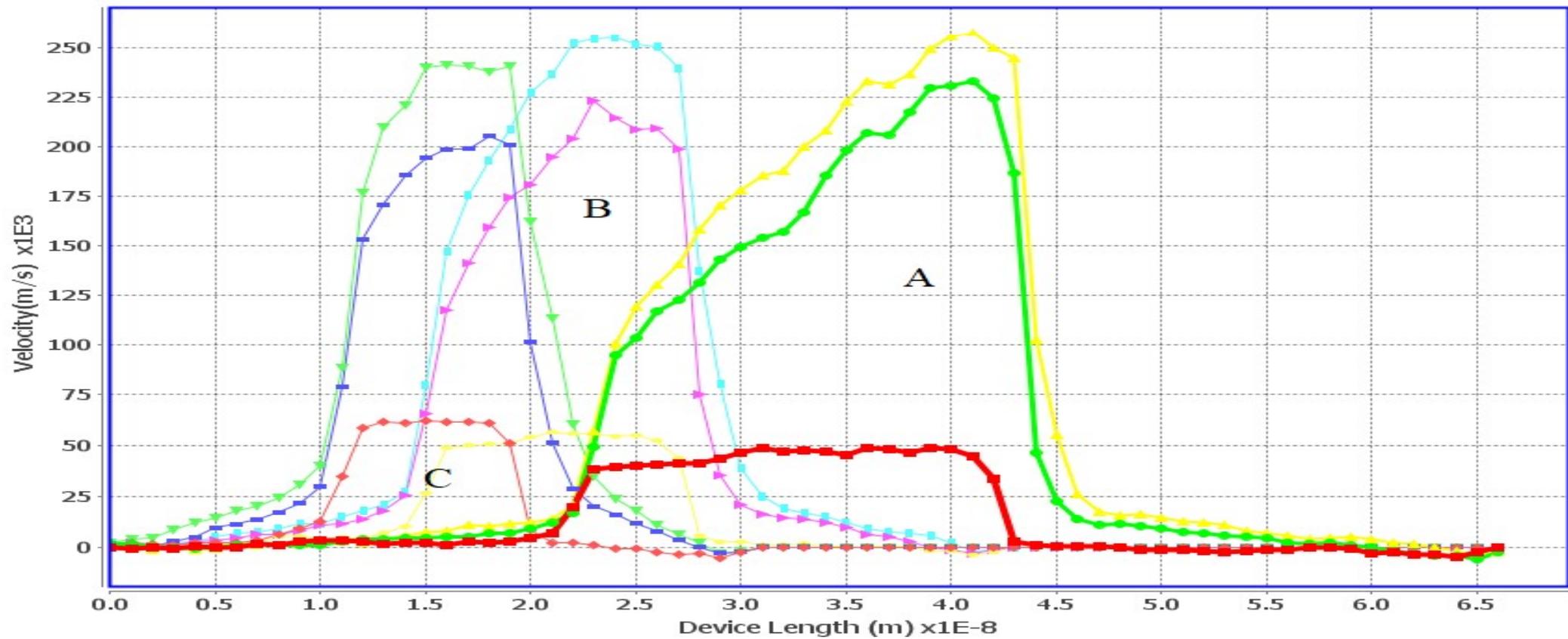
- Intervalley,
- Acoustic and
- Coulomb



# DRIFT VELOCITY



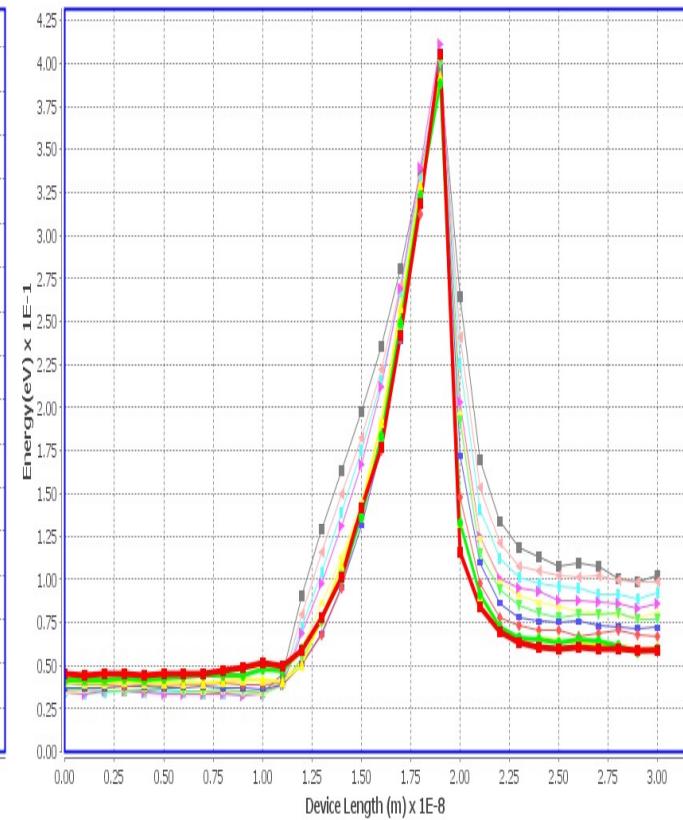
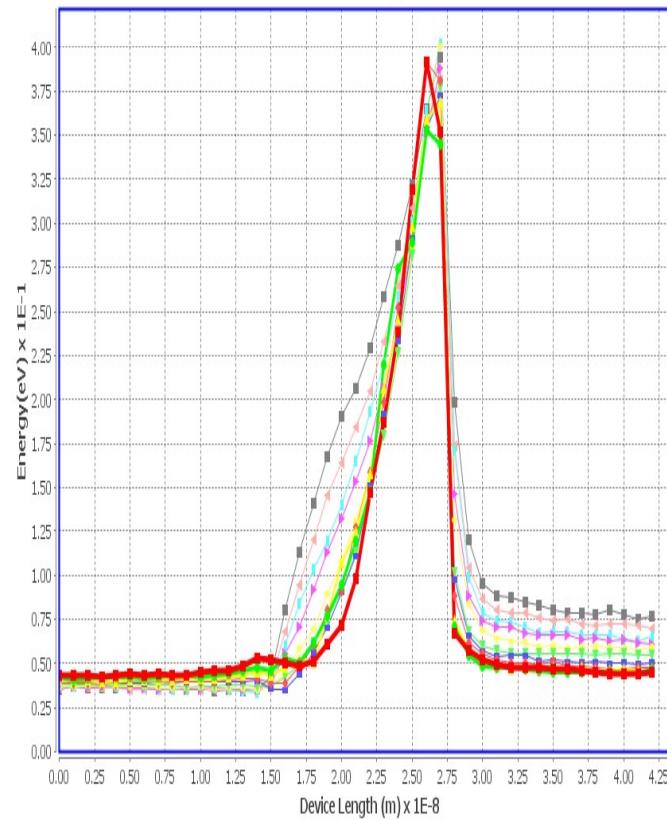
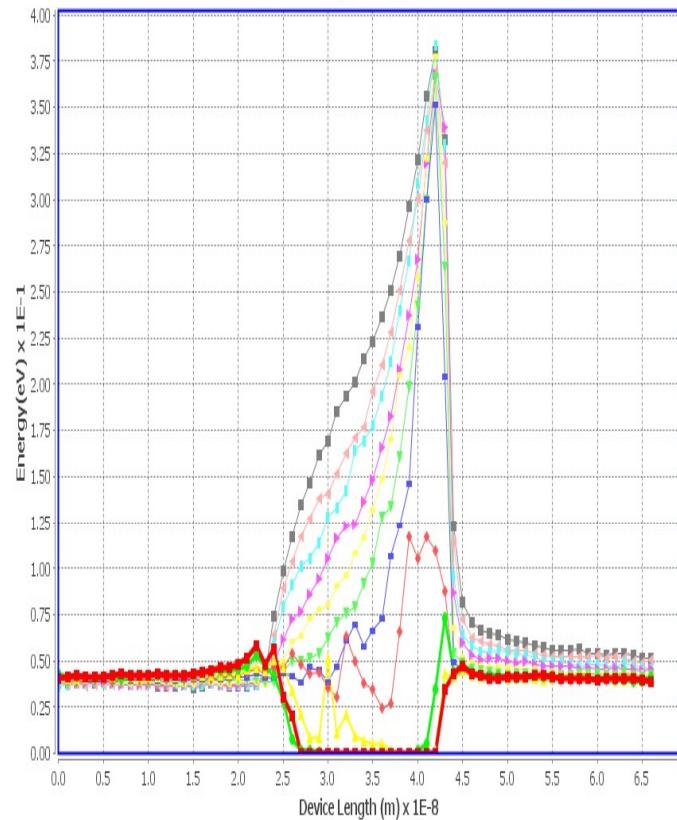
Carrier Drift Velocity for 7nm, 10nm and 14nm (Back Gate off)



Carrier Drift velocity a) 14nm b) 10nm c) 7nm



# CARRIER AVERAGE ENERGY

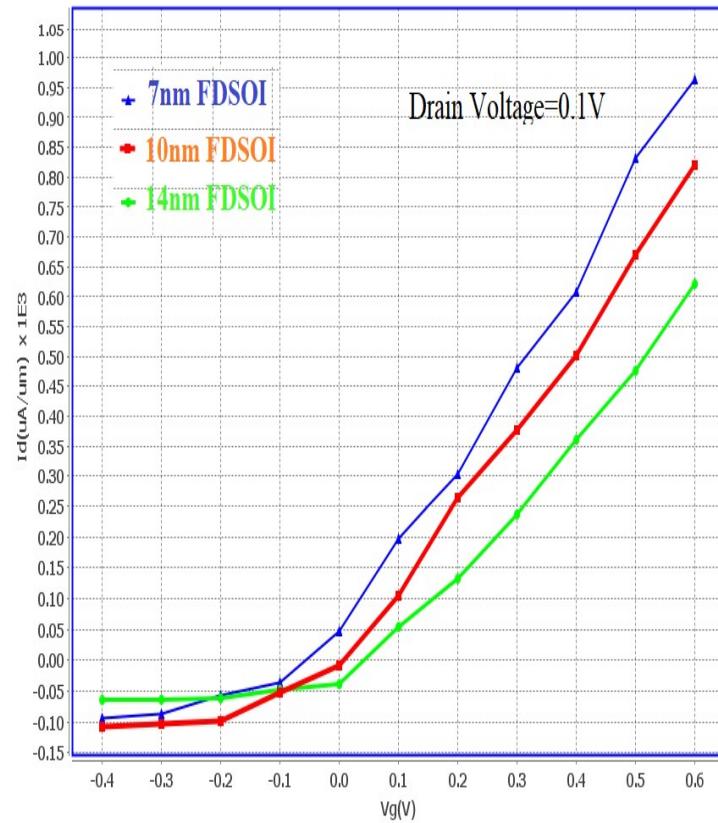


a) 14nm FDSOI MOSFET b) 10nm FDSOI MOSFET c) 7nm FDSOI MOSFET

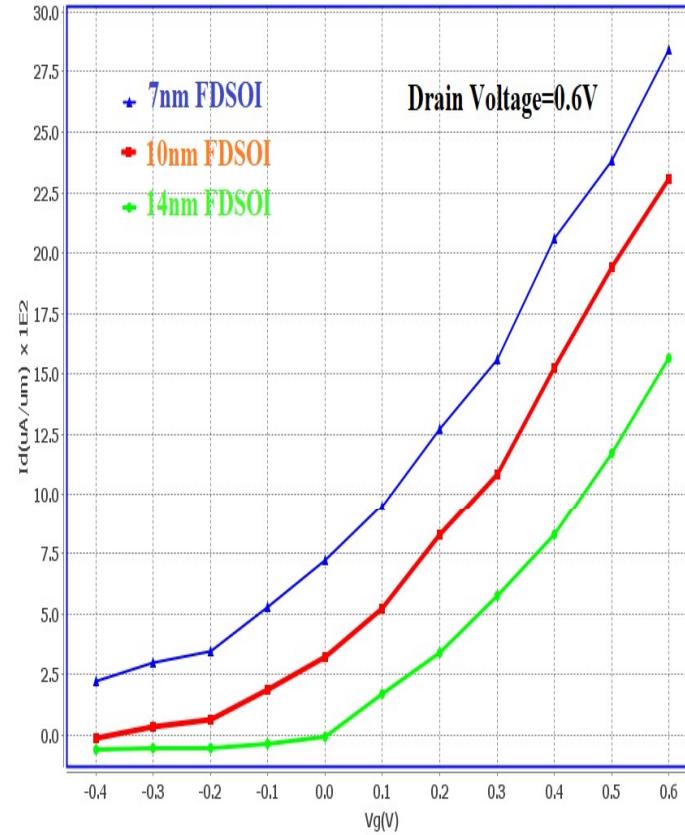
# Transfer $I_d - V_{g_s}$ Characteristics



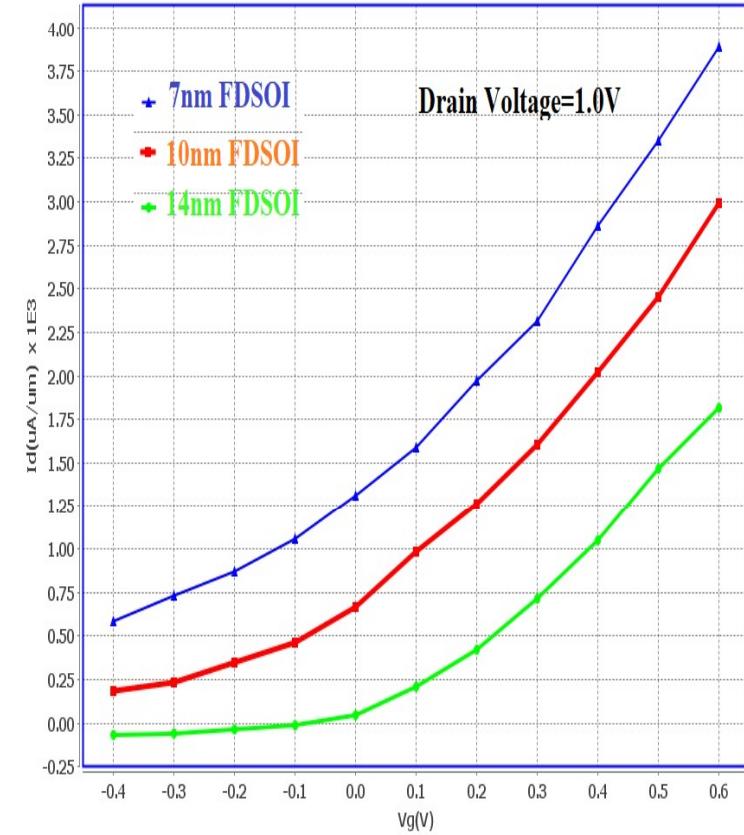
I\_V\_Characteristic



I\_V\_Characteristic



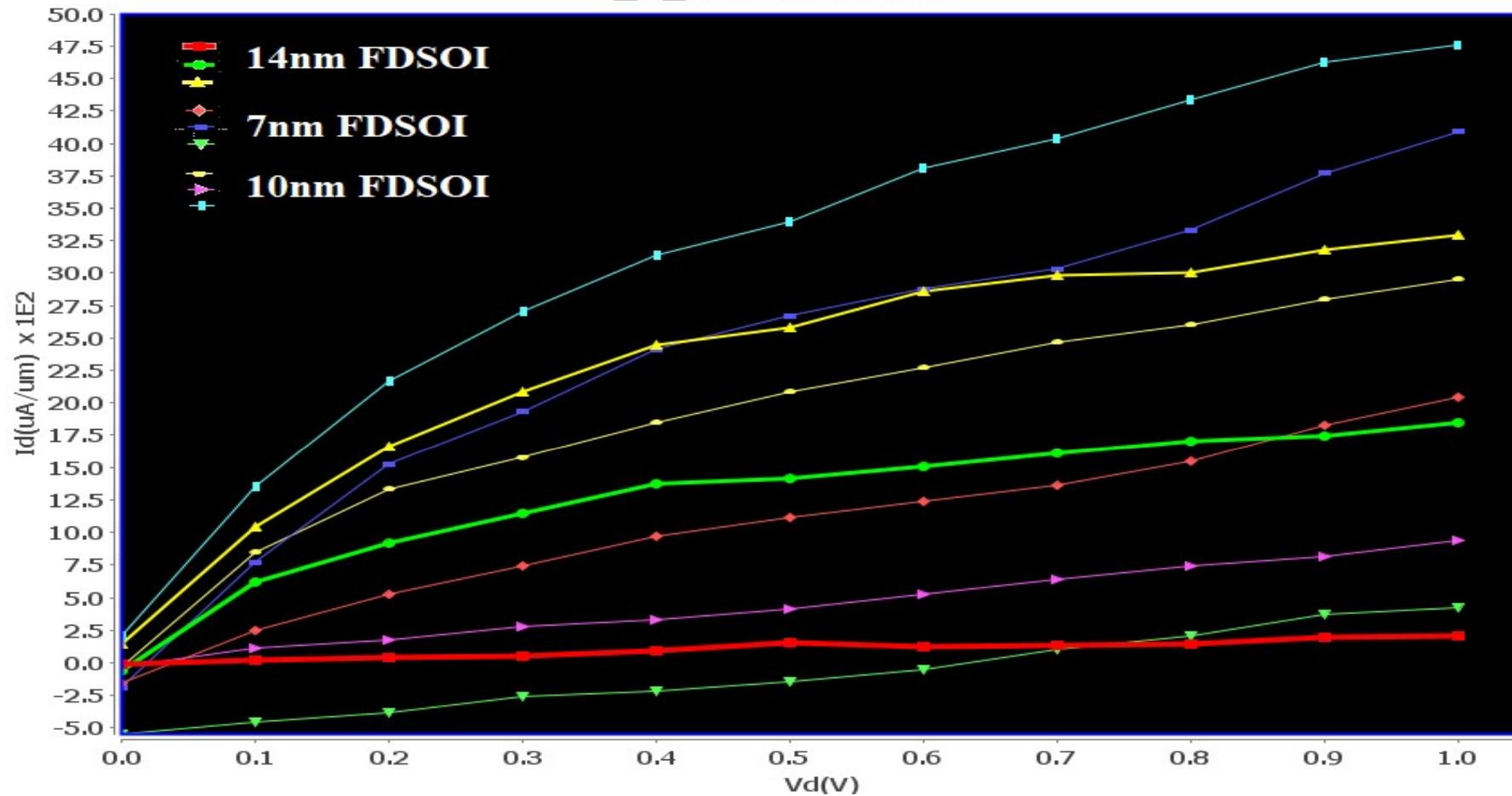
I\_V\_Characteristic



# Single Gate $I_d - V_d$ Characteristics



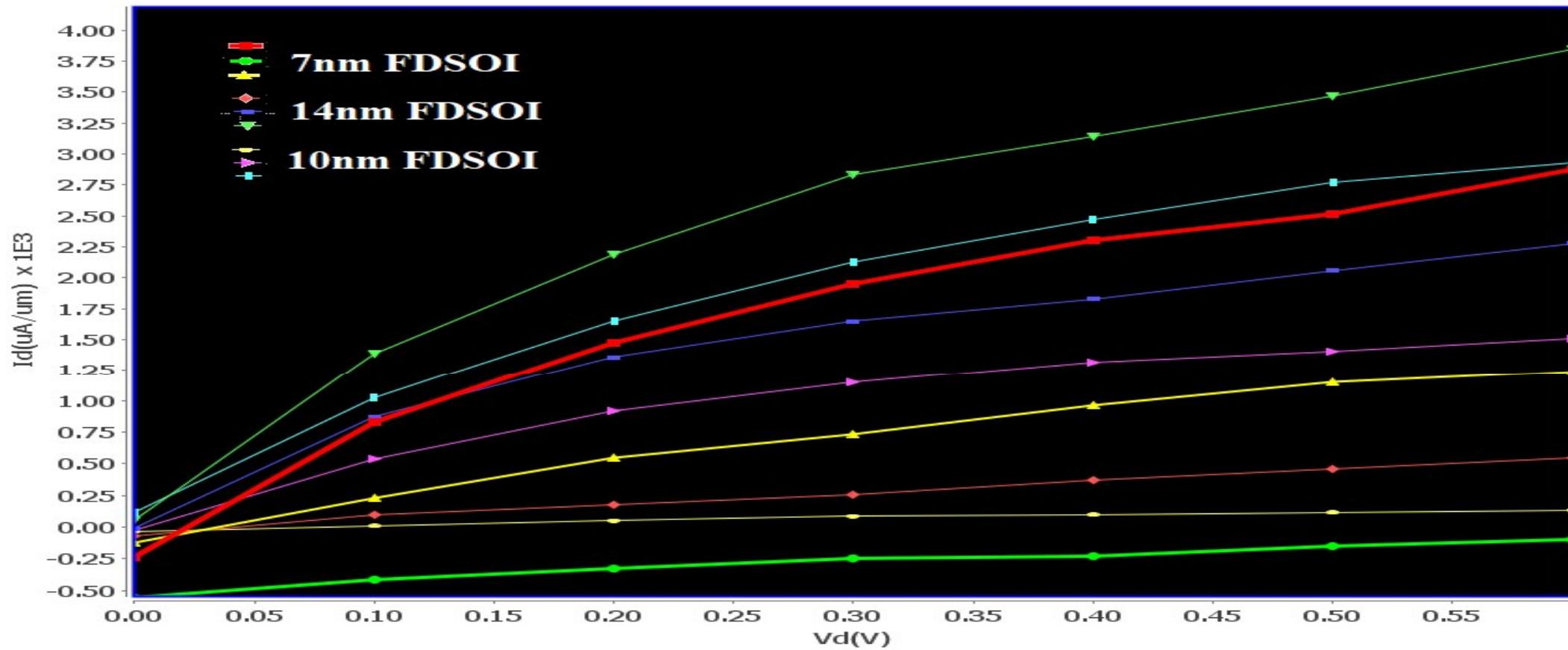
I\_V\_Characteristic



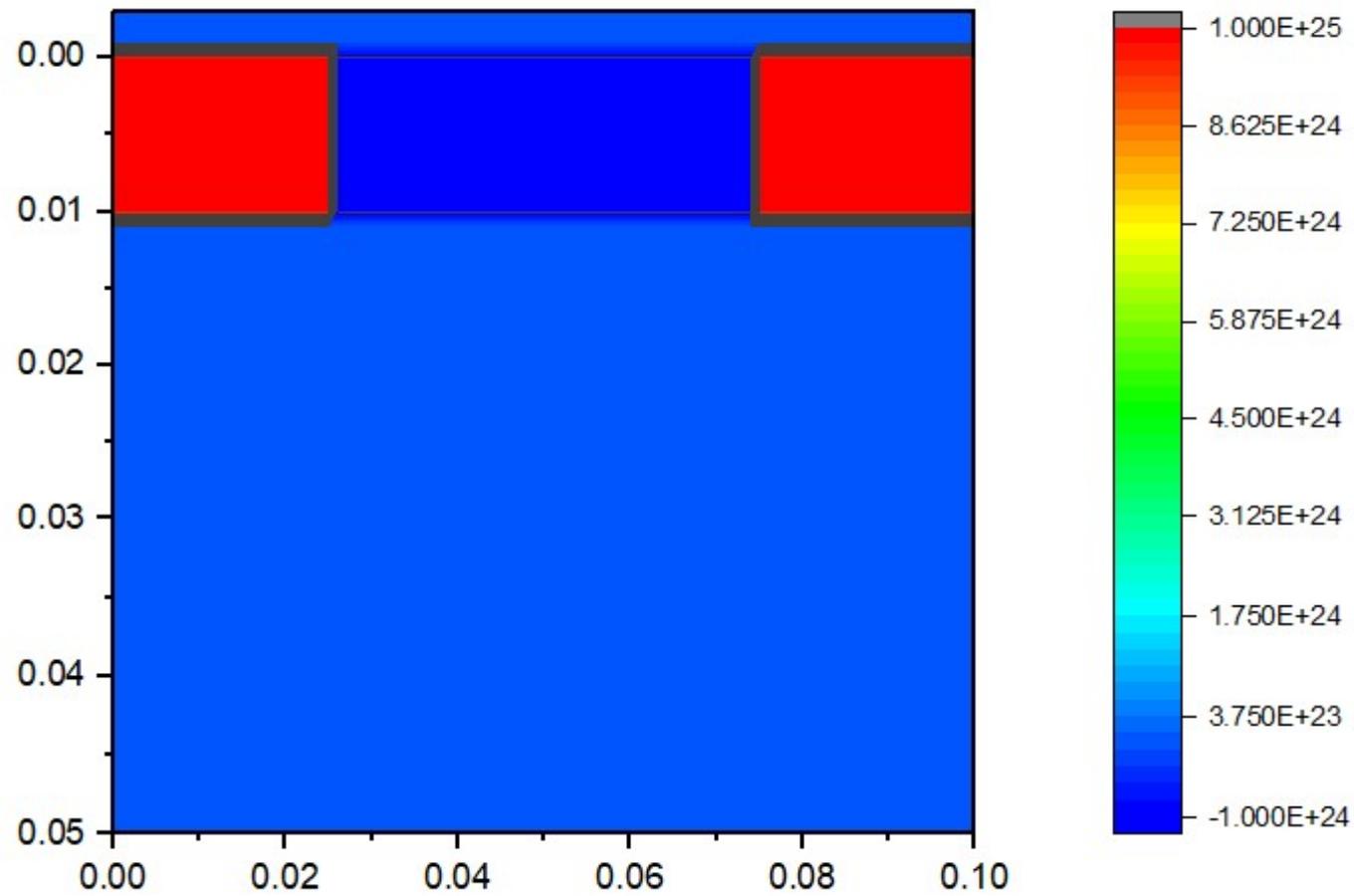
# Dual Gate $I_d - V_d$ Characteristics



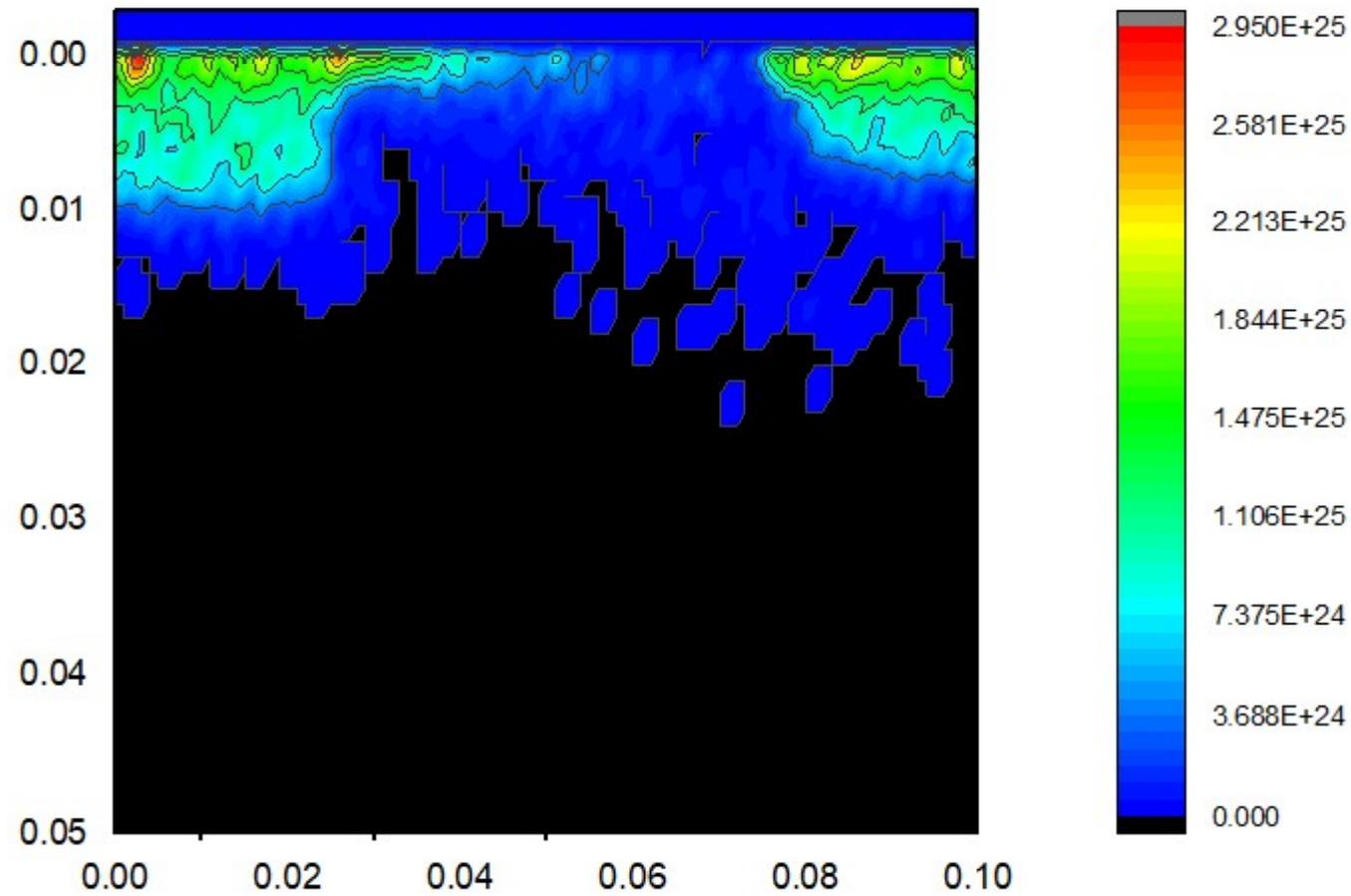
**I\_V\_Characteristic**



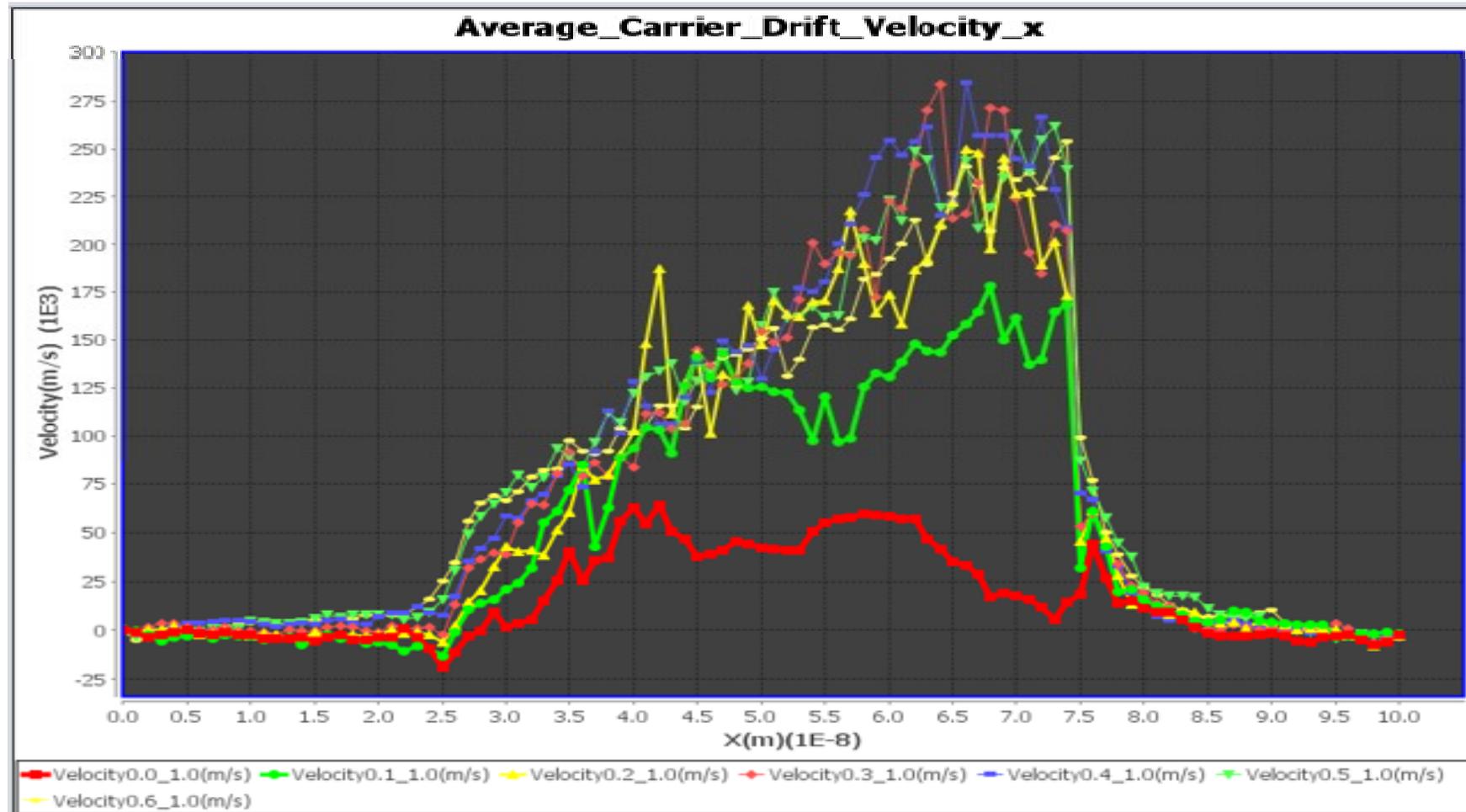
# MOSFET



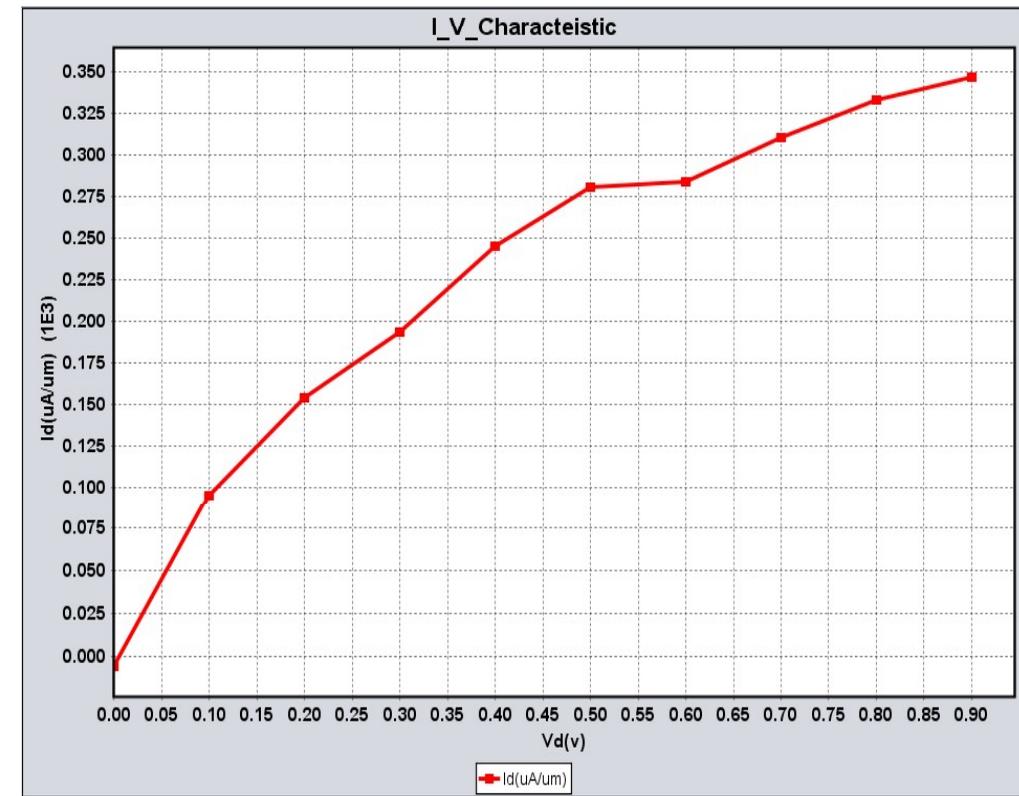
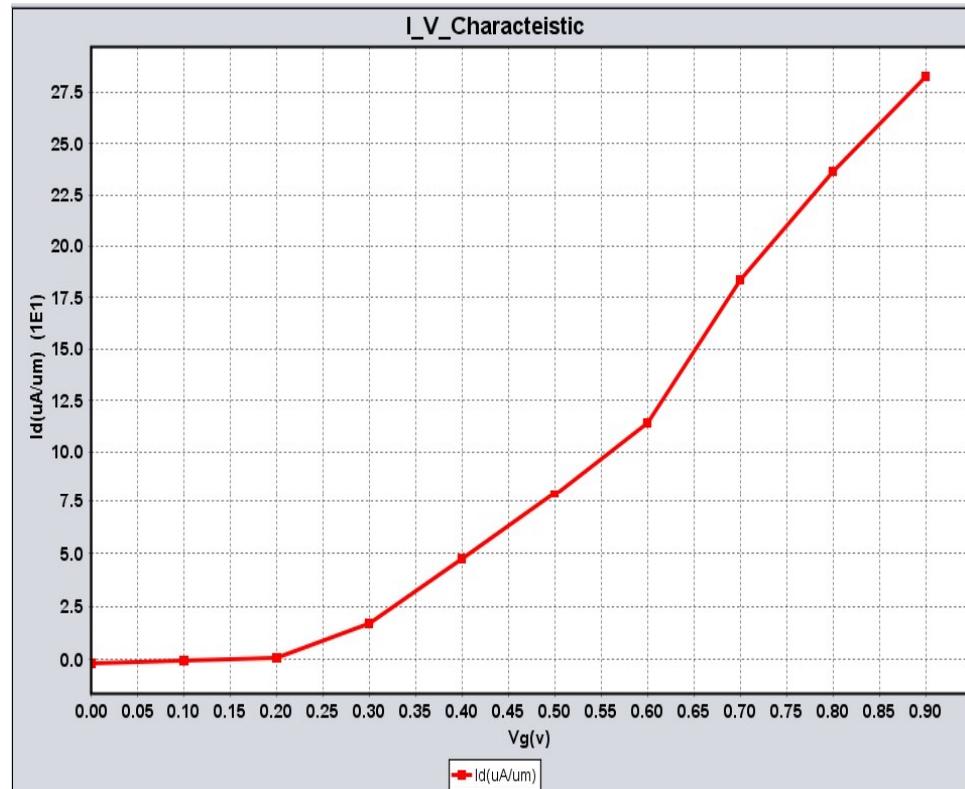
# MOSFET: Carrier Density



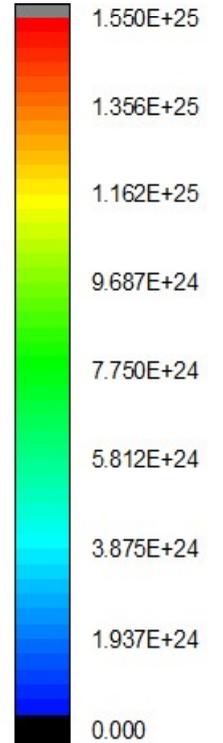
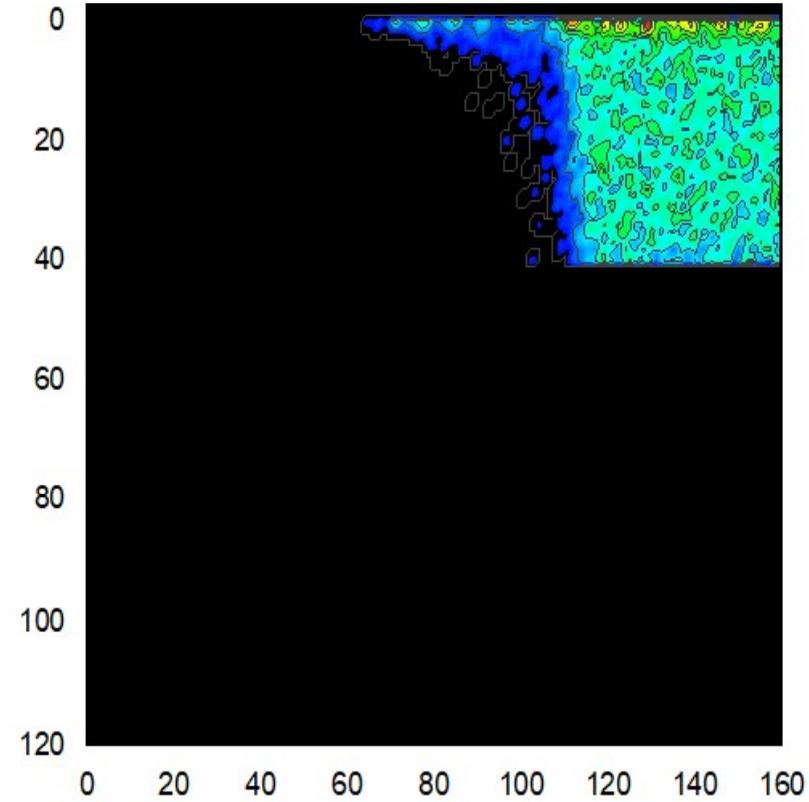
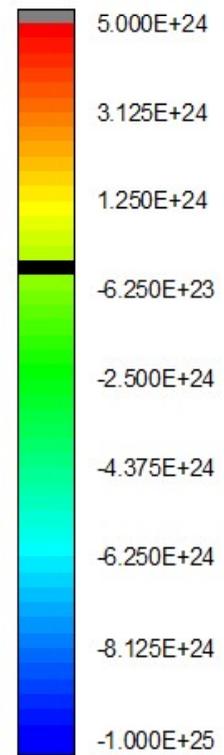
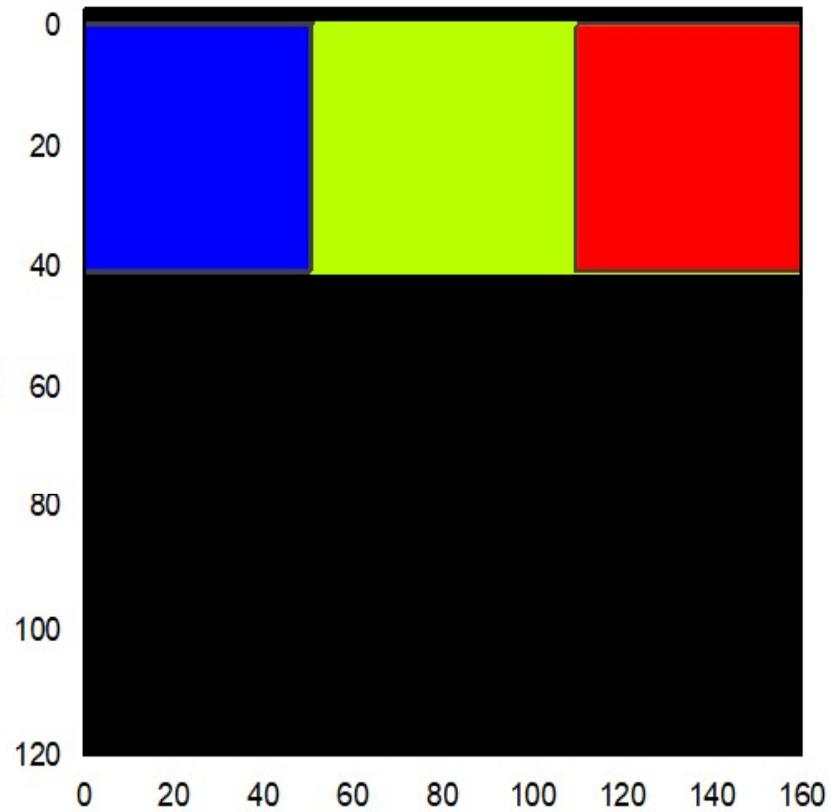
# MOSFET: Carrier Drift Velocity



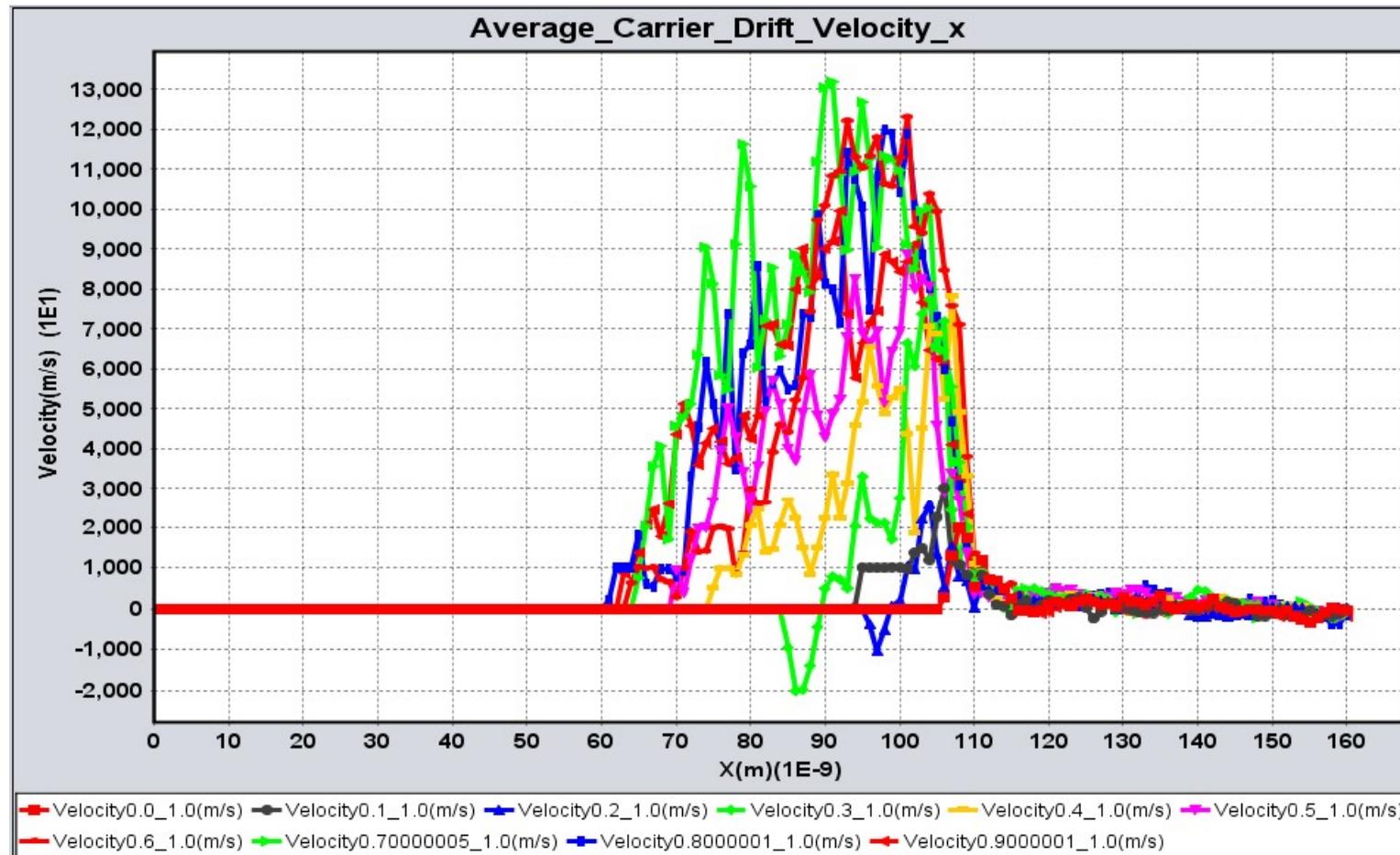
# MOSFET Transfer Characteristics



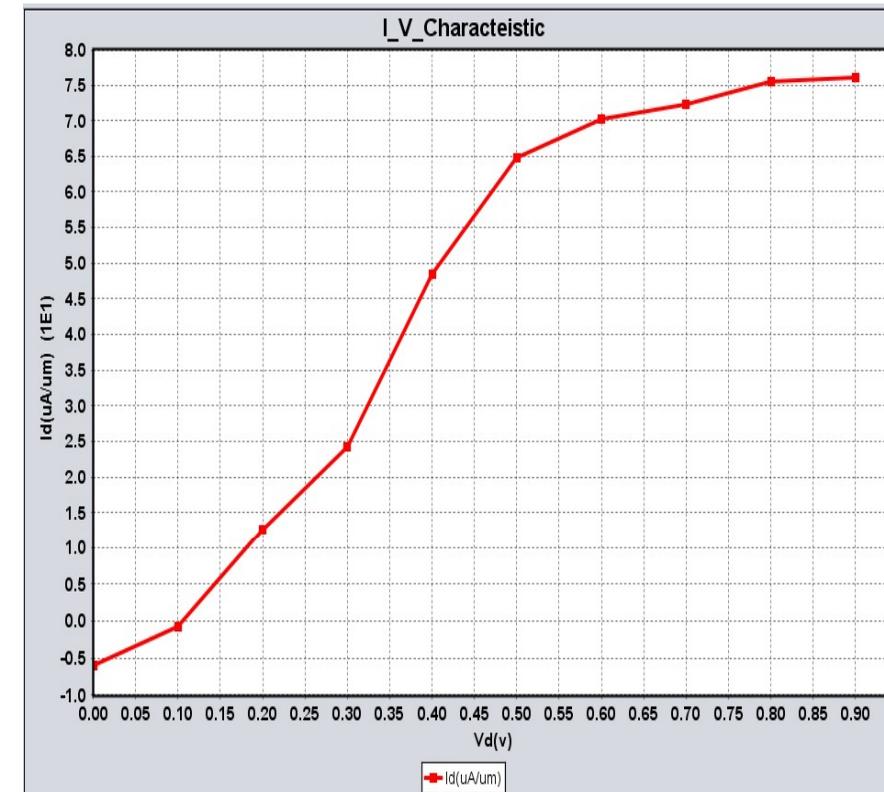
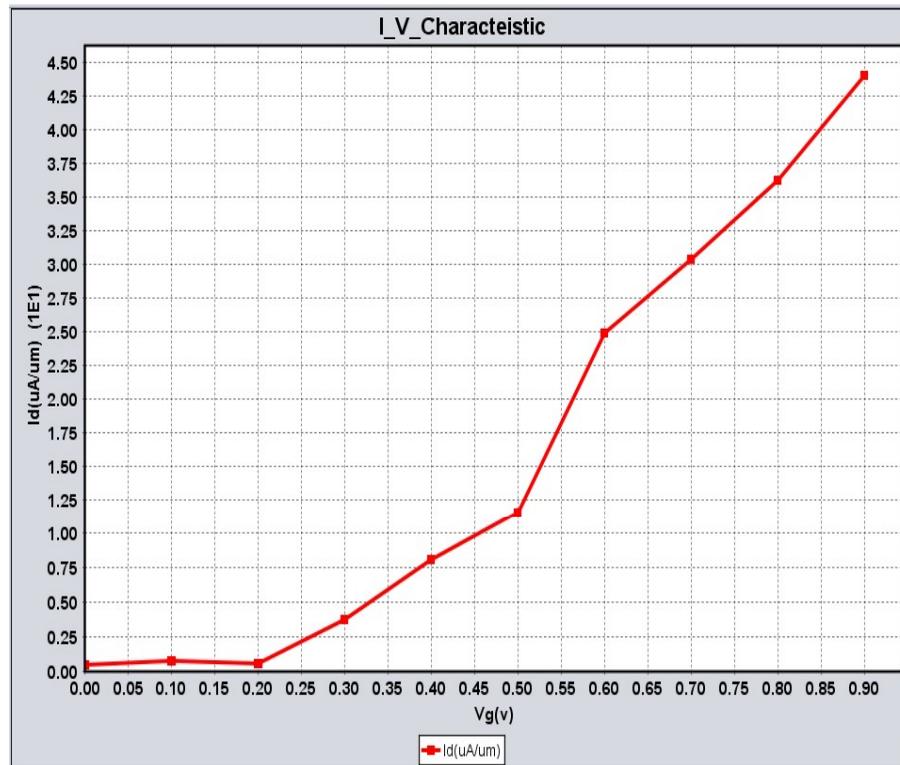
# Tunneling FET



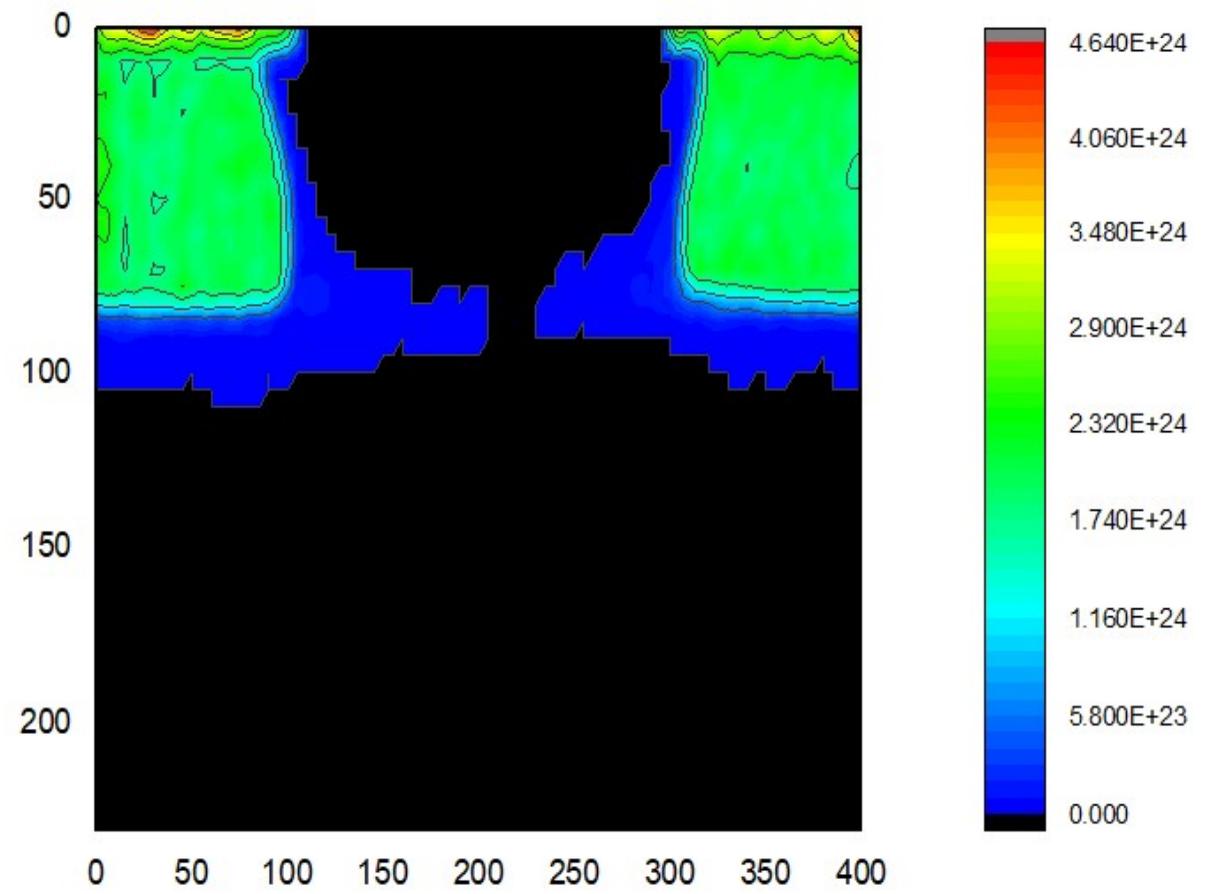
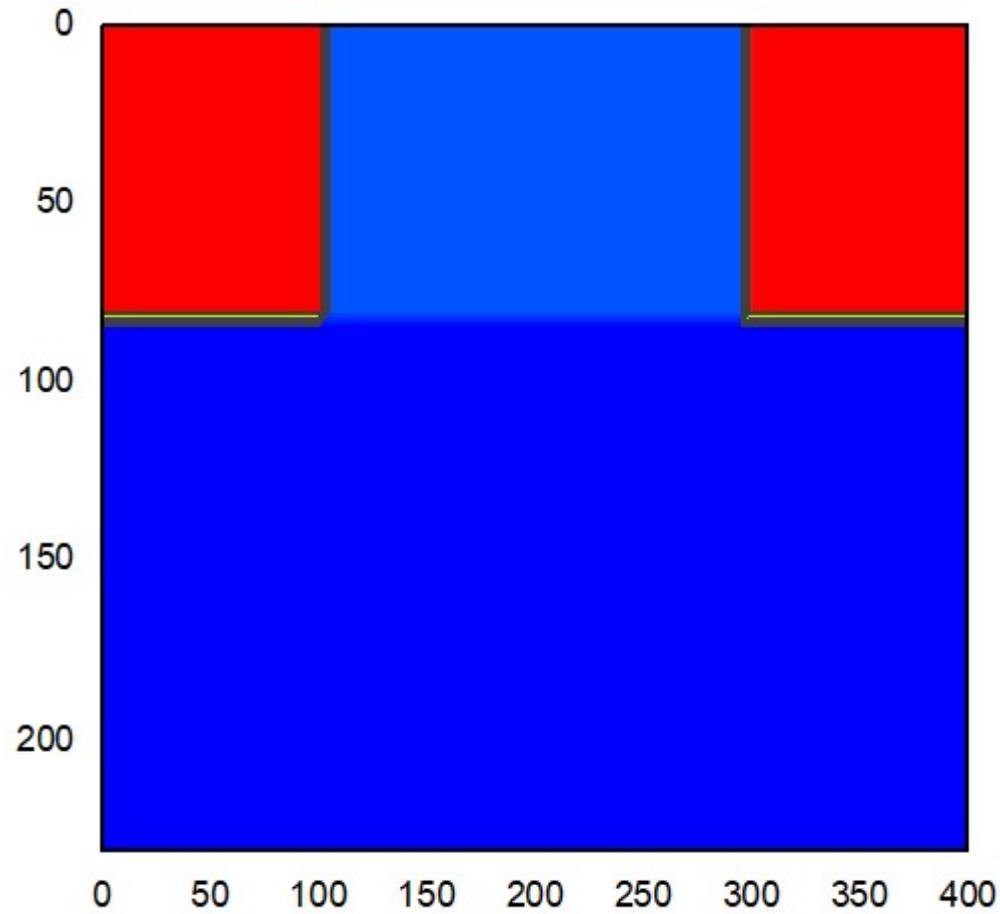
# Tunneling FET



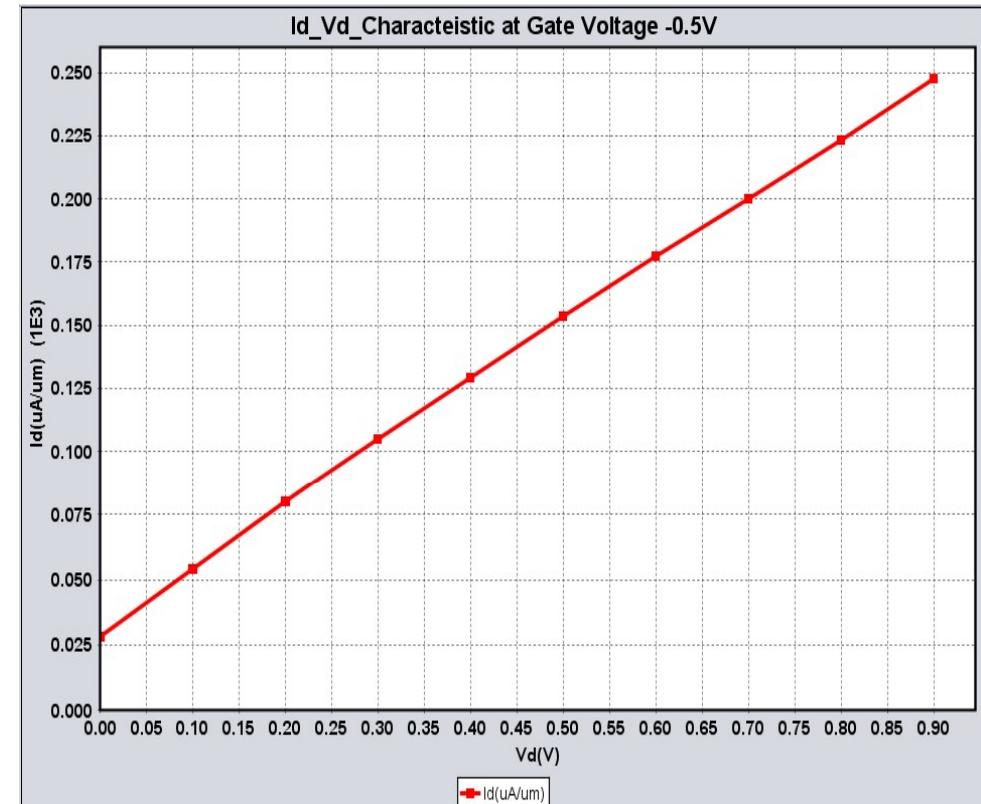
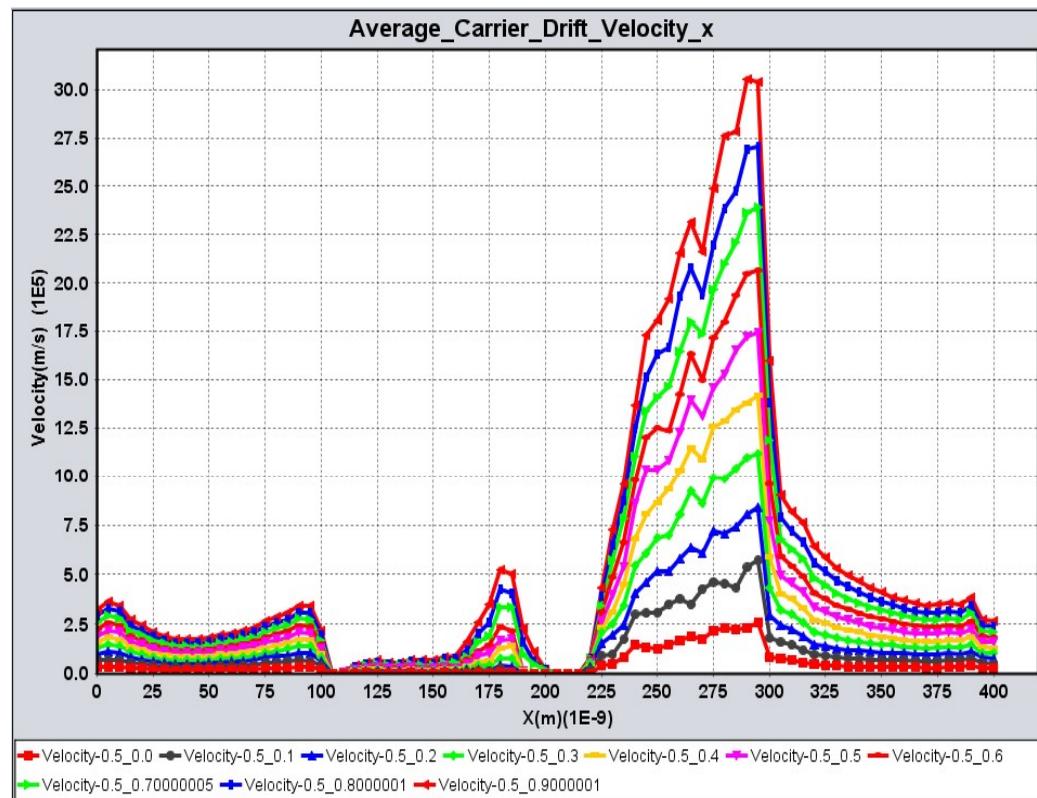
# Tunneling FET Transfer Characteristics



# MESFET



# MESFET



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